

**Notice of References Cited**

Application/Control No.

09/234,233

Applicant(s)/Patent Under  
Reexamination  
LI ET AL.

Examiner

DAVID VU

Art Unit

2818

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**U.S. PATENT DOCUMENTS**

*		Document Number Country Code-Number-Kind Code	Date MM-YYYY	Name	Classification	
*	A	US-5962581-A	10-1999	Hayase et al.	524	588
*	B	US-6140151-A	10-2000	Akram	438	113
	C	US- -				
	D	US- -				
	E	US- -				
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	G	US- -				
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	I	US- -				
	J	US- -				
	K	US- -				
	L	US- -				
	M	US- -				

**FOREIGN PATENT DOCUMENTS**

*		Document Number Country Code-Number-Kind Code	Date MM-YYYY	Country	Name	Classification	
*	N	EP-0942330-A1	09-1999	Europe	Joubert et al.	G03F	095
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	P	- -					
	Q	- -					
	R	- -					
	S	- -					
	T	- -					

**NON-PATENT DOCUMENTS**

*		Include as applicable: Author, Title Date, Publisher, Edition or Volume, Pertinent Pages)
*	U	Timothy W. Weidman et al., New Photodefinable glass etch masks for entirely dry photolithography; Plasma deposited organosilicon hydride polymers (Applied Physics Letters, vol. 62, no. 4, January 25, 1993, pgs 372-374)
*	V	Weidman et al., All dry lithography: Applications of plasma polymerized methylsilane as a single layer resist and silicon dioxide precursor (Journal of Photopolymer Science and Technology, vol. 8, 1995, pgs. 679-686)
*	W	Joubert O et al. : Application of Plasma Polymerized Methylsilane in all dry resist process for 193 and 248 nm lithography (Microelectronic Engineer, vol. 30, no. 1/04, 1 January 1996, pages 275-278)
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\*A copy of this reference is not being furnished with this Office action. (See MPEP § 707.05(a).)  
Dates in MM-YYYY format are publication dates. Classifications may be US or foreign.